PRODUCT/PROCESS
CHANGE NOTIFICATION

PCN 15605

Analog, Power, MEMS & Sensors (APMS)

ST Manufacturing Reshaping (Power_EWS CTN to AMK): Qualification of AMK (Singapore) as new EWS Location.

Issue date: 29th October 2026

Description of the change

Following Corporate PCI 15383 (Early Notification), about Company reshaping program, please be informed that EWS (Electrical Wafer Sorting) of products listed here below will be transferred from ST Catania (Italy) to ST Singapore.

Change Summary:

	Former	New
EWS/Location	ST Catania	ST Singapore

Traceability:

Internal Traceability – Date code – Step tracked in ST production systems and available real time on demand.

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Reason
Die manufacturing: ST manufacturing reshaping program - Corporate PCI - Early Notification.

Impact of change	
Form	Not Impacted
Fit	Not Impacted
Function	Not Impacted
Reliability	Not Impacted
Processibility	Not Impacted

Qualification of the change (plan)

Qualification will be performed according to ST guidelines and ZVEI (ID SEM-TF01) for Automotive products.

		Compliant with ST internal spec and ZVEI Guideline Product and Process Changes (PCN) 5.0 (Automotive products)		
		Line readiness	ED (Electrical Distribution, Cpk, analysis *)	Parametric analysis (Yield, Bin to Bin *)
Product		•	•	•

* Comparing wafers in old vs. new location

Disposition of former products

Delivery of current products will be done until stock depletion.

Qualification results

Qualification report including qualification results is enclosed at the end of this document:

Qualification completion date: Oct-2026.

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Sampling plan
Customer samples are not planned; the switch of production will occur at product validation.

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Qualification Report

Transfer of EWS (Electrical Wafer Sorting) from ST Catania (Italy) to ST Singapore for PnD products

General Information	
Commercial Product	See below list
Product perimeter	Power and Discrete
Product group	APMS
Maturity level	Qualified

Locations	
Diffusion Plant	Multiple
Assembly Plant	Multiple
Reliability Lab	N/A

Reliability Assessment	
Pass	X
Fail	

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1. APPLICABLE AND REFERENCE DOCUMENTS

ZVEI	Change Standard Methodology

2. GLOSSARY

EWS	Electrical Wafer Sorting

3. QUALIFICATION OVERVIEW

3.1. Objective

The objective of this report is to qualify the transfer of EWS (Electrical Wafer Sorting) from ST Catania (Italy) to ST Singapore.

Qualification plan conducted following ZVEI matrix as follow:

	ZVEI DEFAULT	ZVEI WITH CONDITIONS	ST SELECTED	REASON FOR EXCEPTION OF TESTS
AEC-Q101 Revision E	•	•	X	
Parametric Verification	•	•	X	No characterization planned as only EWS is transferred*
Parameter-Analysis: Comparison of current with changed device characterization, electrical distribution	•	•	X	

*Characterization is meant for Final Test transfer, not applicable for this EWS transfer

3.2. Conclusion

Qualification Plan requirements have been fulfilled without exception. Line readiness tests, Electrical Distribution, Cpk, Yield and Bin to Bin analysis and comparison have all shown positive results.
Based on these results, all devices are ready for the EWS transfer from ST Catania to ST Singapore.

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4. PRODUCT OR TEST VEHICLE CHARACTERISTICS

4.1. Device description

Refer to ST specification (some examples below):

4.2. Construction note

	All parts listed in page 6
Wafer/Die fab. information	
Wafer fab manufacturing location	Multiple
Technology	Multiple
Wafer Testing (EWS) information	
Electrical testing manufacturing location	ST Singapore

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5. TEST RESULTS SUMMARY

5.1. Lot information

Lot #	Part Number	Comment
Lot 1	STGWA40IH65DF	Completed
Lot 2	STGIB30M60TS-L	Completed
Lot 3	STGIB30M60S-X	Completed
Lot 4	STGIB30M60S-L	Completed

Detailed results in the chapter below will refer to these references.

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5.2. Test plan

Qualification of the change (plan)

Qualification will be performed according to and ST guidelines and ZVEI (ID SEM-TF01) for Automotive products.

	Compliant with ST internal spec and ZVEI Guideline Product and Process Changes (PCN) 5.0 (Automotive products)		
	Line readiness	ED (Electrical Distribution, Cpk, analysis *)	Parametric analysis (Yield, Bin to Bin *)
Product	•	•	•

*comparing wafers in old vs. new location

5.3. Results summary

Item	Qualification activity	Sample size	Results
EWS line transfer	Line readiness	1 lot	PASS
	ED (Electrical Distribution, Cpk analysis)	1 full lot	PASS
	Parametric analysis (Yield, Bin to Bin)	1 full lot	PASS

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